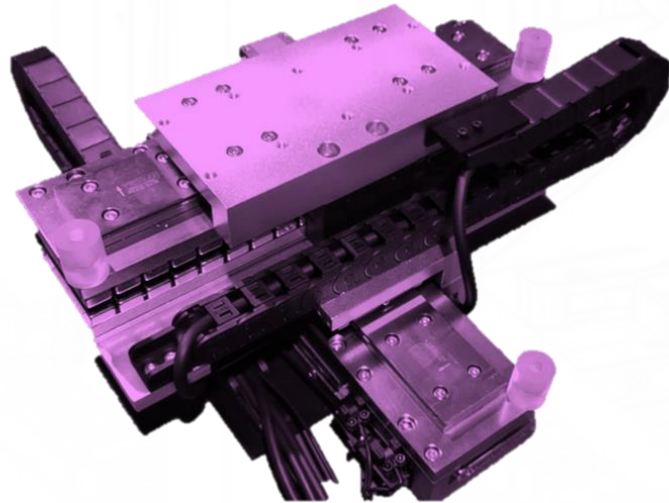


COLLABORATIVE PROJECTS



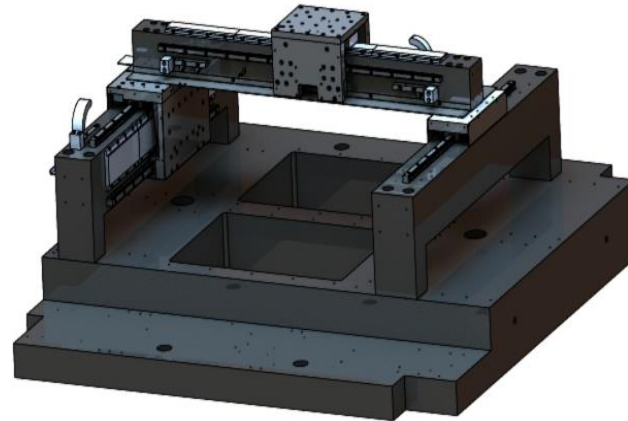
U-shaped two-dimensional positioning platform

Used for laser processing, wafer inspection, etc.



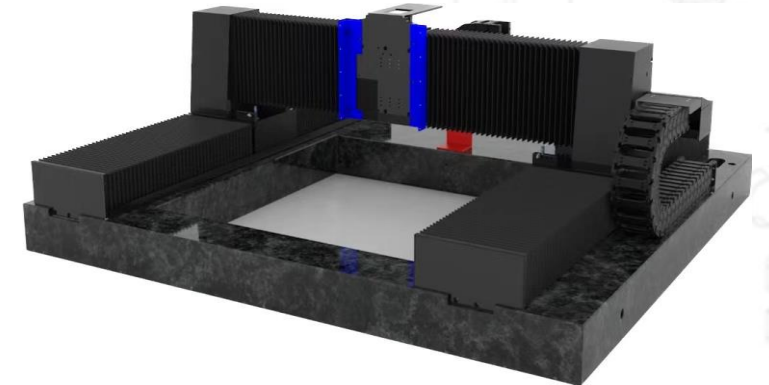
Granite single-drive high-precision positioning platform

Used for laser cutting, dispensing, and semiconductor inspection.



Granite dual-drive high-precision positioning platform

Used for laser cutting, dispensing, and semiconductor inspection.



Continuous thrust in the X-axis	Maximum thrust in the X-axis	Continuous thrust in the Y-axis	Maximum thrust in the Y-axis
51 N	288 N	102 N	576 N
Repeatability accuracy	Resolution	Load	
±1 μm	0.1 μm	2 kg	

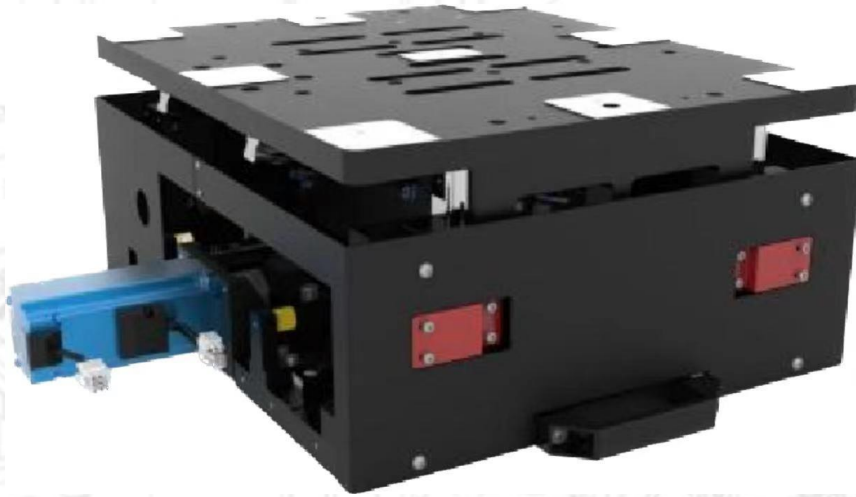
Repeatability accuracy of the XY axis	Maximum velocity	Maximum acceleration	Straightness of a single axis
±2 μm	1000 mm/s	1.0 g	±1.5 μm
Motion flatness	Maximum load	Stroke	
2.5 μm	10 kg	500×300 mm	

Repeatability accuracy of the XY axis	Maximum velocity	Maximum acceleration	Straightness of a single axis
±1 μm	1000 mm/s	1.0 g	±1.5 μm
Maximum load	Stroke		
10 kg	700×600 mm		

Collaborative projects

Lifting platform

Used for semiconductor inspection, optical lens inspection, and precision machining, etc.



Positioning accuracy	Repeatability accuracy	Maximum velocity	Maximum acceleration	Stroke of the screw guide
±5 µm	±3 µm	300 mm/s	0.2 g	5 mm
Verticality	Flatness	Load	Stroke	
±3 µm	0.03/500 mm	60 kg	23 mm	

Precision hollow wafer positioning platform

Used for wafer cutting.



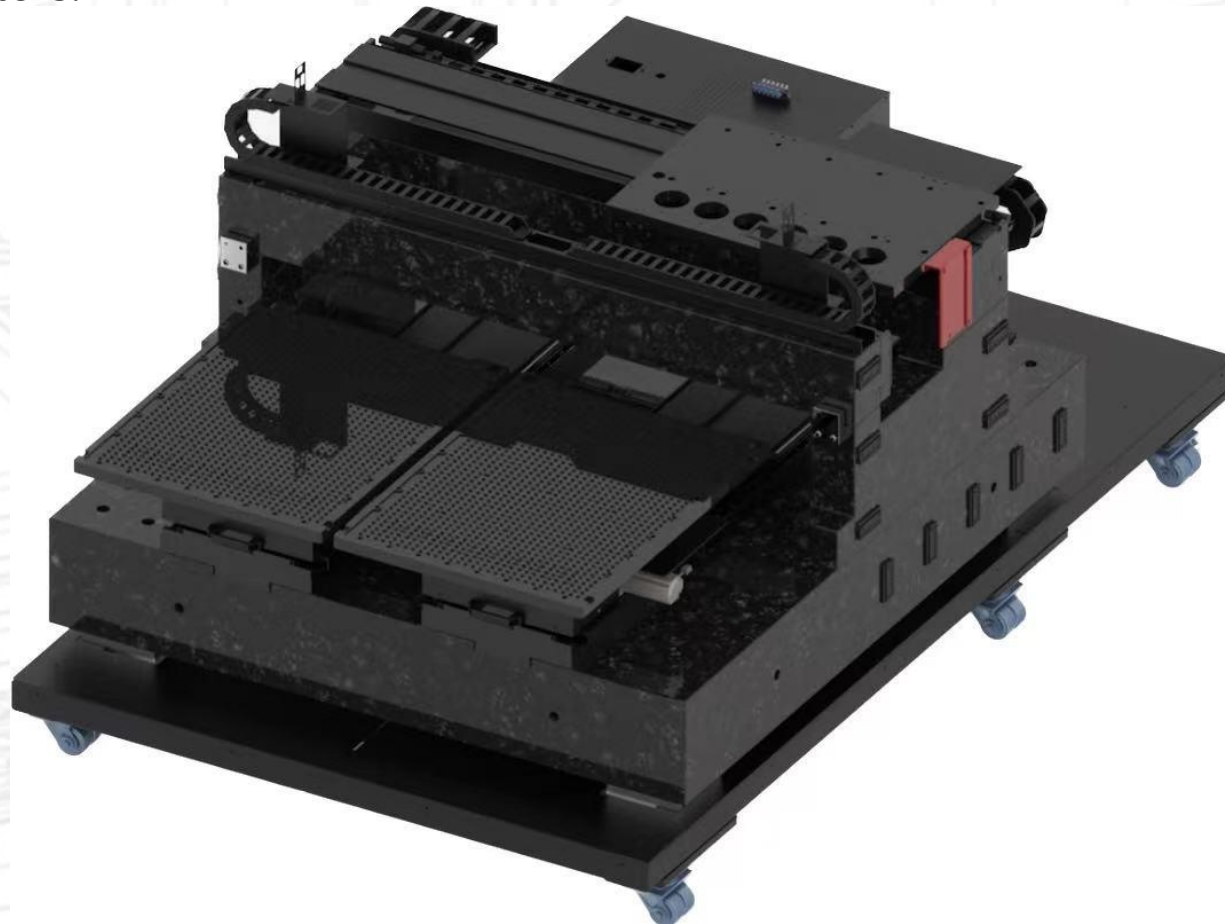
Positioning accuracy of the X-axis	Positioning accuracy of the Y-axis	Repeatability accuracy of the X-axis	Repeatability accuracy of the Y-axis	Maximum velocity
±2.5 µm	±2.0 µm	±1.1 µm	±1.0 µm	1000 mm/s
Maximum acceleration	Load capacity of the X-axis	Load capacity of the Y-axis	Stroke of the X-axis	Stroke of the Y-axis
1.5 g	10 kg	X+10 kg	400 mm	300 mm

COLLABORATIVE PROJECTS



40-50 micron linewidth seven-axis LDI exposure platform

Used in semiconductor production lines, microelectronics manufacturing, LCD displays, printed circuit board production, and other industries. Equipped with high-precision optical grating position feedback and controlled by direct drive with ironless linear motors.



Description	Axis Number	Specification	Actual measurement data
Straightness	Y1	±5 um	8.4 um
	Y2	±5 um	3.9 um
	X	±8 um	5.2 um
	X1/X2	±8 um	6.2/4.6 um
Straightness	Y1	±12 um	8.6 um
	Y2	±12 um	5.4 um
	X	±12 um	6.7 um
	X1/X2	±10 um	6.5/6.6 um
Yaw	Y1	5"	4.9"
	Y2	5"	4.0"
	X	10"	3.5"
	X1/X2	±10"	13.1/14.7"
Pitch	Y1	20"	5"
	Y2	20"	5.8"
	X	5"	8.4"
Positioning accuracy	Y1	±2.5 um	1.4 um
	Y2	±2.5 um	1.3 um
	X	±2.5 um	0.5 um
	X1/X2	±2.5 um	0.8/0.5 um
	Z1	±2.5 um	2.2 um
Repeatability accuracy	Z1	±10 um	3.5 um
	Y1	±1.5 um	2.5 um
	Y2	±1.5 um	1.6 um
	X	±1.5 um	1.4 um
	X1/X2	±1.5 um	1.5/2.2 um

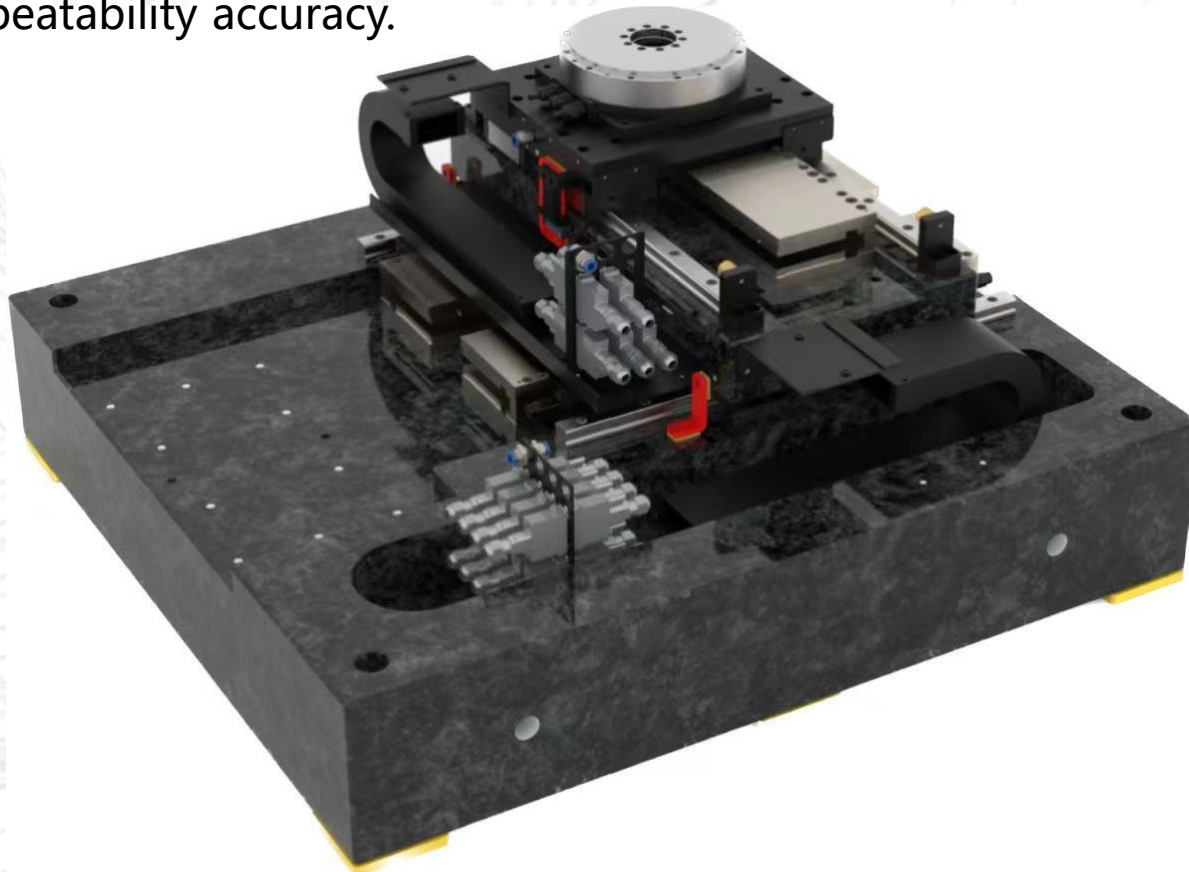
COLLABORATIVE PROJECTS



AOI inspection platform

Applied in various fields such as automotive electronics, display inspection (digital tubes, LCD screens, LED displays), and product positioning.

Equipped with non-contact high-precision grating rulers, it possesses excellent dynamic performance, positioning accuracy, and repeatability accuracy.



Description	Stage Specification
Effective travel distance of the X-axis and Y-axis	160×160 mm
Effective travel distance of the R-axis	±15°
Positioning accuracy of the X-axis and Y-axis	±1 μm
Positioning accuracy of the R-axis	±2.5 arcsec
Repeatability accuracy of the X-axis and Y-axis	±0.5 μm
Repeatability accuracy of the R-axis	±1.5 arcsec
Straightness of the X-axis and Y-axis	±2 μm
Velocity of the R-axis	120 rpm
Velocity of the X-axis and Y-axis	1000 mm/s
Acceleration of the X-axis and Y-axis	1 g
End deflection (R-axis)	10 μm
DD end deflection (R-axis)	2 μm
Load (R-axis)	5 kg+DD
Overall flatness after superposition (R-axis)	10 μm

Collaborative Projects



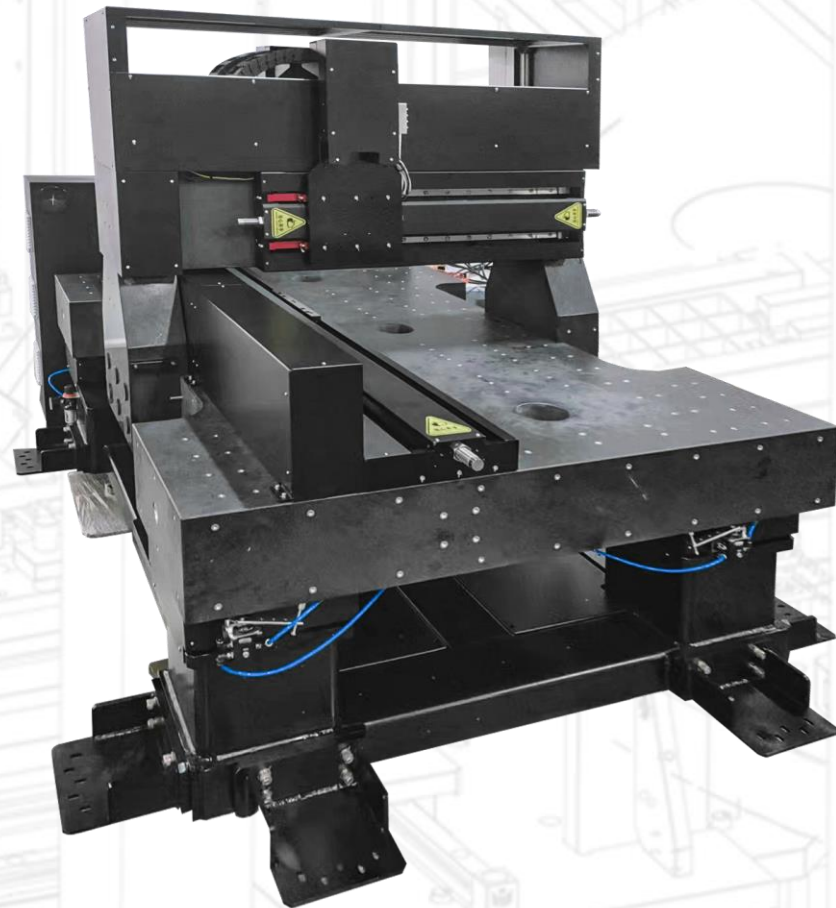
LED chip inspection platform Used for LED chip inspection



Type	X0-axis	Y0-axis	Y1-axis	Z0-axis	Z1-axis
Load	30 kg	12 Kg	40 kg	30 kg	12 kg
Positioning accuracy	+/- (3+L/250) um	+/- 15 um	+/- 10 um	12 mm Minimum	12 mm Minimum
Stroke	2050	1400mm	194mm	-	-
Length of linear axis	3140 mm	mm	mm	-	-
Length of slide table	890 mm	230 mm	mm	-	-
Resolution	5 nm or better	0.1um or better	0.1um or better	0.2 um	0.2 um
Acceleration	0.5G (Average) @ 66.7% Jerk	0.5G (Average) @ 66.7% Jerk	0.25G (Average) @ 66.7% Jerk	50 mm/sec^2	50 mm/sec^2
Velocity	1000 mm/s(Max)	1000 mm/s (Max)	500 mm/s (Max)	-	-
Velocity fluctuation	0.2% Max @ Velocity = 400mm/s	-	-	-	-
Repeatability accuracy	+/-1 um	+/-1 um	+/-1 um	+/- 1 um	+/- 0.1 um
Vertical straightness	+/-15 um	+/-10 um	+/- 12 um over full range	-	-
Horizontal straightness	+/- 2 um over 200mm +/- 15 um over full range	+/-10 um	+/- 10 um	-	-
Settling time	200 msec @ 0.2um p-p	200 msec @ 0.2um p-p	200 msec @ 0.2um p-p	-	-
X0-axis Y0-axis orthogonality	20um p-p		-	-	-

Collaborative Projects

LED chip inspection platform Used for LED chip inspection

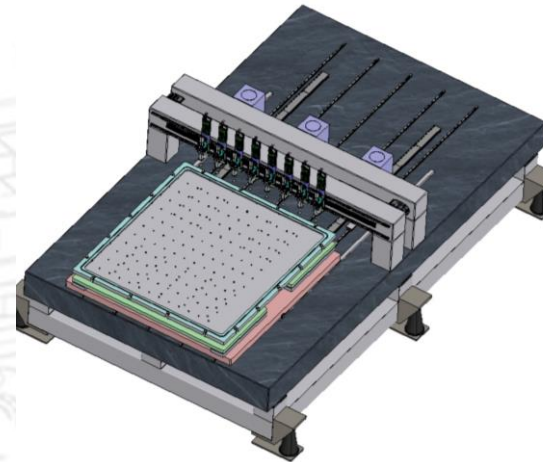
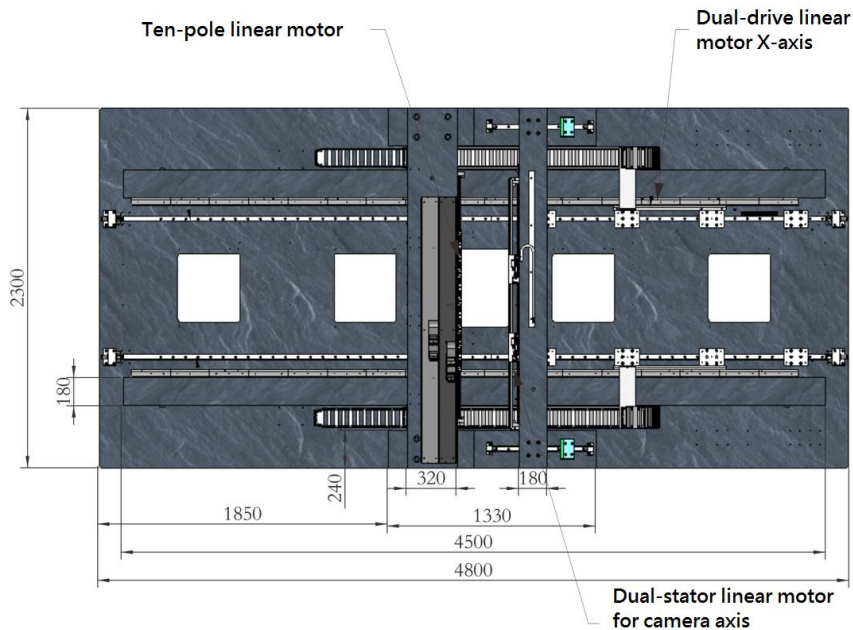
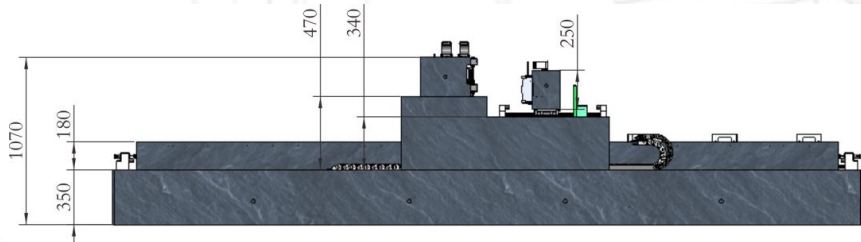


	X0-axis	Y0-axis	Y1-axis	Z1-axis	Z0-axis
Load	15kg	12 Kg for each	20 kg	20 kg	12 kg
Positioning accuracy	+/- (3+L/500) um	+/- 10 um	+/- 10 um	-	-
Stroke	1330	430	430	12 mm Minimum	-
Length of linear axis	mm	mm	mm	-	-
Length of slide table	310	mm	mm	-	-
Resolution	5nm or better	0.1um or better	0.1um or better	0.2 um	-
Acceleration	0.5G (Average) @ 66.7% Jerk (Acc=0.75G, jerk =112500mm/s^3@1000mm/s)	0.5G (Average) @ 66.7% Jerk (Acc=0.75G, jerk =112500mm/s^3@1000mm/s)	0.25G (Average) @ 66.7% Jerk (Acc=0.375G, jerk =56250mm/s^3@500mm/s)	50 mm/sec^2	-
Velocity	1000 mm/s (Max)	1000 mm/s (Max)	500 mm/s (Max)	0.2 um	-
Velocity	0.2% Max @ Velocity = 200mm/s	-	-	-	-
Repeatability accuracy	+/-1 um	+/-1 um	+/-1 um	+/- 1 um	-
Vertical straightness	+/-10 um	+/-10 um	+/- 10 um	-	-
Horizontal straightness	+/- 2 um over 200mm; +/- 10 um over full range	+/-10 um	+/- 12 um over full range	-	-
Settling time	200 msec @ 0.2um p-p	200 msec @ 0.2um p-p	200 msec @ 0.2um p-p	-	-
X0-axis Y0-axis orthogonality	-	10um	-	-	-
X0-axis Y1-axis orthogonality	-	-	10um	-	-
X0-axis Y1-axis Z1-axis orthogonality	-	-	-	10um	-

COLLABORATIVE PROJECTS

Glass marking motion platform

Used for glass marking in the front-end array process.



Description	Axis Number	Specification
Horizontal straightness XX	X1, X2	18 um
	Y	10 um
Vertical straightness YY	X	18 um
	Y	24 um
Orthogonality	X-Y	12 um/500 mm
Parallelism	X1 -X2	20 um
Yaw	Y	3/500 mm
	X	3 m/s ²
Maximum acceleration	Y	3 m/s ²
	X	800 mm/s
Maximum velocity	Y	1000 mm/s
	X1, X2	6 um
Positioning accuracy	Y	10 um
	X	2 um
Repeatability accuracy	Y	2 um(One-way), 4 um(Two-way)
	Stroke of X-axis & Y-axis	3100×3200 mm

COLLABORATIVE PROJECTS



8-10 micron linewidth LOI exposure air flotation platform

Used for LOI exposure machines for carrier boards, flexible boards, HDI boards, and multilayer board digital imaging.

Stroke of Y-axis & X-axis : 1350X160 mm

Verticality between dual axes : 2 arcsec

Straightness of the XY axes : 6 μ m

Y-axis pitch : 2.5 arcsec

Positioning accuracy of the XY axes after compensation : 0.8 μ m

XY axes Yaw : 1 arcsec

Repeatability accuracy of the XY axes : 0.3 μ m

X-axis pitch : 0.7 arcsec

Product Features: This motion platform is based on high-precision marble, utilizing passive isolation. It is equipped with air-floating guides, ironless linear motors, and a 50 nm resolution Inductive Steel Scale.

Overall dimensions: 3350X2090X2010 mm.

We provide ACS docking scripts, controller parameter usage, PID tuning, and other debugging and training services.

The whole machine is guaranteed for one year.

Application Fields: IC carrier boards, FPCBs, HDIs, and multilayer boards.

Applicable Processes: Inner and outer layers.

Process Resolution: 8-10 micrometer linewidth.


Exposure Area: 700X600 mm (suction cup size).

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Thanks